

MATERIAL DECLARATION SHEET



| | | | | |
|-----------------|------------------------|-----|---|--|
| Material Number | CDDFN10-2574N | | | |
| Product Line | Semiconductor Products | | | |
| Compliance Date | 2017/5/9 | | | |
| RoHS Compliant | Yes | MSL | 3 | |

| No. | Construction Element(subpart) | Homogeneous Material | Material weight [mg] | Homogeneous Material\ Substances | CASRN if applicable | Materials Mass % | Material Mass % of total unit wt. | Subpart mass of total wt. (%) |
|-----|-------------------------------|----------------------|----------------------|----------------------------------|---------------------|------------------|-----------------------------------|-------------------------------|
| 1 | Wafer | Silicon | 0.56000 | Silicon | 7440-21-3 | 100.00% | 4.444% | 4.444% |
| 2 | Lead frame | Copper Alloy | 5.40500 | Copper | 7440-50-8 | 94.00% | 42.897% | 45.636% |
| | | | 0.02990 | Silicon | 7440-21-3 | 0.52% | 0.237% | |
| | | | 0.19723 | Nickel | 7440-02-0 | 3.43% | 1.565% | |
| | | | 0.00776 | Magnesium | 7439-95-4 | 0.14% | 0.062% | |
| | | | 0.00575 | Iron | 7439-89-6 | 0.10% | 0.046% | |
| | | | 0.02875 | Zinc | 7440-66-6 | 0.50% | 0.228% | |
| | | | 0.00288 | Manganese | 7439-96-5 | 0.05% | 0.023% | |
| | | Plating | 0.00086 | Gold | 7440-57-5 | 0.01 | 0.007% | |
| | | | 0.00575 | Palladium | 7440-05-3 | 0.10% | 0.046% | |
| | | | 0.06613 | Nickel | 7440-02-0 | 1.15 | 0.525% | |
| 3 | Epoxy | Polymer | 0.01600 | CP Bisphenol A Diglycidyl ether | 25036-25-3 | 20.00% | 0.127% | 0.635% |
| | | | 0.02000 | Carbinol acetate | 112-15-2 | 25.00% | 0.159% | |
| | | | 0.00800 | Epoxy resin | 25068-38-6 | 10.00% | 0.063% | |
| | | | 0.03120 | Epoxy resin | Proprietary | 39.00% | 0.248% | |

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|---|---------------|--------------|----------------|------------------------------|--------------|--------|---------|---------|
| | | | 0.00400 | Dapsone | 80-08-0 | 5.00% | 0.032% | |
| | | | 0.00080 | 3-Aminopropyltriethoxysilane | 919-30-2 | 1.00% | 0.006% | |
| 4 | Wire | Noble metal | 0.23996 | Gold | 7440-57-5 | 99.99% | 1.9048% | 1.905% |
| | | | 0.00002 | Misc. not to declare | / | 0.01% | 0.0002% | |
| 5 | Mold Compound | Polymer | 0.17910 | Epoxy resin | Trade Secret | 3.00% | 1.421% | 47.380% |
| | | | 0.17910 | Phenol resin | Trade Secret | 3.00% | 1.421% | |
| | | | 4.79093 | Silica (Amorphous) A | 60676-86-0 | 80.25% | 38.024% | |
| | | | 0.80595 | Silica (Amorphous) B | 7631-86-9 | 13.50% | 6.396% | |
| | | | 0.01493 | Carbon Black | 1333-86-4 | 0.25% | 0.118% | |
| | | Total weight | 12.6 mg | | | | | |

This Document was updated on: 2017/5/9

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.